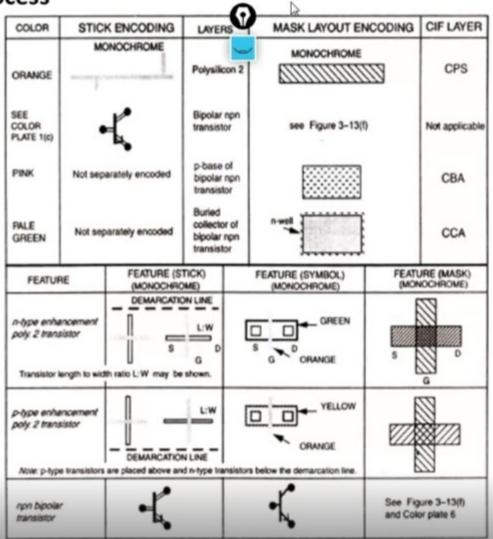
CMOS process CIF LAYER COLOR MASK LAYOUT ENCODING STICK ENCODING \* Thinox = n-diff. + p-diff. + CAA transistor channels CM (n° GREEN CNA CPF Polysilicon RED Encoding as in Encoding as in Color plate 1(a) Color plate 1(a) CMF Metal 1 BLUE CC Contact out BLACK COG GRAY Overglass p\* mask CAA YELLOW (STICK) p-diffusion CPA (p\*active) green outline here for clarity either CPP p\*mask YELLOW Not shown on diagram DARK BLUE OR CMS Metal 2  $\blacksquare$ 13 CVA BLACK VIA Demarcation line BROWN CPW p-well edge is shown as a demarcation line in stick diagrams V<sub>00</sub> or × CC BLACK V<sub>SS</sub> contact FEATURE (SYMBOL) FEATURE (MASK) FEATURE (STICK) FEATURE Demarcation line n-type enhancement L: W mode transistor (as in Color plate 1(a)) Transistor length to width ratio L:W may be shown. enhancement mode translator Demarcation line p"mask Note: p-type transistors are placed above and n-type below the demarcation line

**BiCMOS** process



# nMOS Design Style

#### The layout of nMOS involves

- 1. n-diffusion and other thinoxide regions –green
- 2. Polysilicon 1-red
- 3. Metal 1-blue
- 4. Implant-yellow
- 5. Contacts-black or brown

The Transistor is formed wherever poly crosses n-diffusion (red over green) and all diffusion wire (interconnection) a re n-type (green)

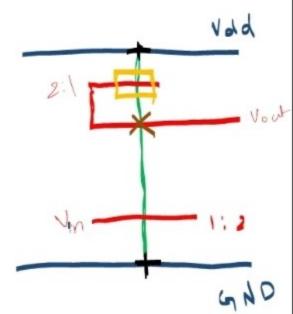
## Steps for Layout

- Draw the meta(blue) VDD and GND rails
- Thinox(green) paths may be drawn between rails for inverters
- Depletion mode transistors connected from output point to VDD and pull-down structure of enhancement mode connected between output and GND
- Implants for depletion mode transistor
- Signal paths may also be switched by pass transistor
- Leaf-cell boundaries are conveniently shown on stick diagram

### **Examples**

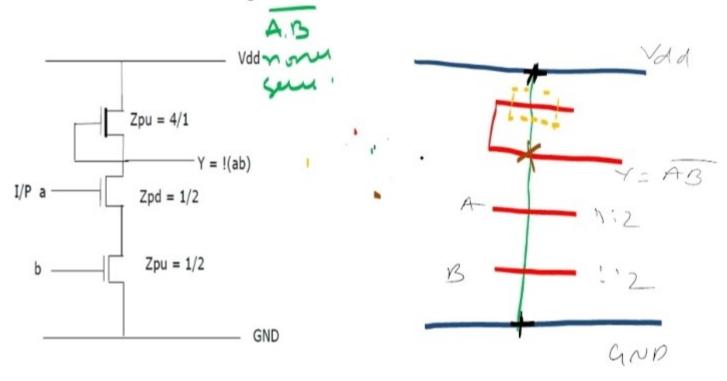
#### nMOS Inverter





## nMOS Depletion load NOR 2:1 Zpu = 2/1Y=!(a+b) Zpd = 1/2Zpd = 1/2CIND GND

### nMOS Depletion load NAND



#### Buses, Control Signals, Interconnections and leaf Boundaries

